TOSHIBA BIPOLAR DIGITAL IC SILICON MONOLITHIC

TD62930P,TD62930F

THREE-CHANNEL SMALL-SIGNAL IGBT GATE DRIVER

The TD62930P and TD62930F are drivers using 5 V-signal input to output the signals required to drive IGBT gates.

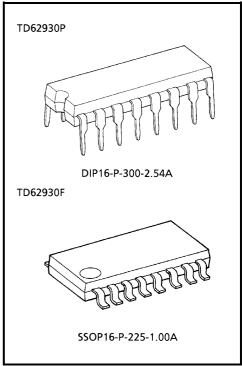
TD62930P / F is the most suitable for low–side drive of a miniature IGBT to use for inverter for the household electric appliances mainly.

The outputs are separated into high-side and low-side outputs. This separation simplifies the IGBT gate on / off timing control. Two output signals are assigned for one input signal. The high-side output is high-level for high-level input, and high impedance for low-level input. The low-side output is high impedance for high-level input, and low-level for low-level

FEATURES

input.

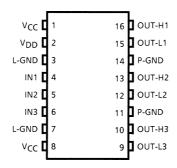
- Power supply voltage (maximum rating)
 High-voltage block power supply voltage VCC = 30 V
 Low-voltage block power supply voltage VDD = 7 V
- Output current (maximum rating)
 High-side peak current I_{OUT} = -0.4 A (max)
 Low-side peak current I_{OUT} = 0.4 A (max)
- Input-output response speed tpHL, tpLH $\leq 1 \mu s$ (max)
- Package: DIP16 / SSOP16 (1.00 mm pitch)



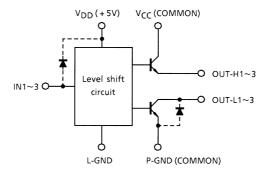
Weight

DIP16-P-300-2.54A : 1.11 g (Typ.) SSOP16-P-225-1.00A: 0.14 g (Typ.)

PIN ASSIGNMENT (TOP VIEW)



INTERNAL EQUIVALENT CIRCUIT



PIN DESCRIPTION

PIN No.	PIN NAME	FUNCTION
1, 8	V _{CC}	30 V supply pins
2	V _{DD}	5 V supply pin
3, 7	L-GND	Ground pins for 5 V supply
4, 5, 6	IN1~3	Input pins for 5 V output control signals
11, 14	P-GND	Ground pins for 30 V supply
9, 12, 15	OUT-L1~3	Low-side output pins
10, 13, 16	OUT-H1~3	High-side output pins

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	PIN / PACKAGE	SYMBOL	RATING	UNIT	
Power Supply Voltage	V _{CC}	V_{CC}	30	V	
Power Supply Voltage	V _{DD}	V_{DD}	7	V	
Input Voltage	IN1~3	V _{IN}	-0.5~V _{DD} + 0.5	V	
	OUT-H1~3	V	0~20 (Ta = −20~85°C)	V	
Output Valtage	001-61~3	V _{OUT (H)}	0~30 (Ta = −20~70°C)	7 '	
Output Voltage	OUT-L1~3	V	-0.5~20 (Ta = -20~85°C)	V	
	001-11-3	V _{OUT} (L)	-0.5~30 (Ta = -20~70°C)	, v	
High-level Output Peak Current	OUT-H1~3	IOPH (Note 1)	-0.4	A / ch	
Low-level Output Peak Current	OUT-L1~3	IOPL (Note 1)	+0.4	A / ch	
Operating Frequency	IN1~3	f	25	kHz	
Deves a Diseise ation	DIP16	P _{D1} (Note 2)	1.47 (FREE AIR)	W	
Power Dissipation	SSOP16	P _{D2} (Note 2)	0.78 (ON PCB)	W	
Operating Ambient Temperature		T _{opr}	-20~85	°C	
Storage Temperature		T _{stg}	-55~150	°C	

Note 1: Output pin current

The pulse width of the output pin current at peak is \leq 1 μ s, 300 pps.

Note 2: When ambient temperature exceeds 25°C

Derate the power dissipation of DIP-type devices at 11.76 mW / 1°C (device only) and

Derate the power dissipation of SMD-type devices at 6.24 mW / 1°C (mounted on the board).

RECOMMENDED OPERATING CONDITIONS (Unless otherwise specified, Ta = -20 to $70^{\circ}C$)

CHARACTERISTIC		PIN	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Innut Valtage	High level	IN1~3	V _{IH}	V _{CC} = 15 V, V _{DD} = 4.5~5.5 V	3.5	_	_	٧
Input Voltage	Low level	111113	V_{IL}		_	_	1.0	
Input Current	High level	IN1~3	I _{IH}	V _{CC} = 15 V, V _{DD} = 4.5~5.5 V	_	_	5	mA
	Low level	1141~3	I _{IL}		_	_	-5	
Input Power Supply Voltage		V _{CC}	V _{CC}		10	15	25	- V
		V_{DD}	V_{DD}		4.5	5.0	5.5	
Output Current		OUT-H1~3	IOH (DC)	V _{CC} = 20 V, V _{DD} = 4.5 V	_	_	-0.1	
		001-61~3	IOH (Peak)		_	_	-0.35	
		OUT-L1~3	IOL (DC)	V _{CC} = 20 V, V _{DD} = 4.5 V	_	_	0.1	
		001-11-3	IOL (Peak)		_	_	0.35	
Operating Temperature			T _{opr}	V _{CC} = 30 V, V _{DD} = 5.5 V	-20	25	70	°C
				V _{CC} = 20 V, V _{DD} = 5.5 V	-20	25	85	

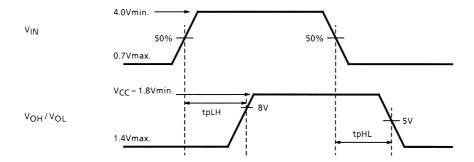
ELECTRICAL CHARACTERISTICS (Unless otherwise specified, Ta = −20 to 70°C)

CHARACTERISTIC		PIN	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Input Current	High level	IN1~3	I _{IH}	V _{CC} = 15 V, V _{IN} = 5 V	0.1	0.2	0.4	mA
Input Current	Low level	1111~3	I _{IL}	V _{CC} = 15 V, V _{IN} = 0 V	_	0	_	
Output Voltage	High level	OUT-H1~3	V _{OH}	V_{CC} = 15 V, V_{IH} = 5 V, R_{LH} = 100 Ω	VCC -4.0	VCC -1.9	VCC -1.0	V
	Low level	OUT-L1~3	V_{OL}	V_{CC} = 15 V, V_{IL} = 0 V, R_{LL} = 100 Ω	0.3	0.5	2.5	
Dissipation Current 1		V _{DD}	I _{DDL}	V _{DD} = 5.5 V, V _{IH} = 0 V, Ta = 25°C	_	1.5	3.0	- mA
				V_{DD} = 5.5 V, V_{IH} = 0 V, Ta = -20~85°C	_	_	3.5	
			I _{DDH}	V _{DD} = 5.5 V, V _{IH} = 5 V, Ta = 25°C	_	1.8	3.5	
				V _{DD} = 5.5 V, V _{IH} = 5 V, Ta = −20~85°C	_	_	4.0	
Dissipation Current 2		Vcc	ICCL	V _{CC} = 30 V, V _{DD} = 5.5 V, V _{IH} = 0 V, Ta = 25°C	_	10.2	15.0	- mA
				V _{CC} = 30 V, V _{DD} = 5.5 V, V _{IH} = 0 V	_	_	18.0	
			ı	V _{CC} = 30 V, V _{DD} = 5.5 V, V _{IH} = 5 V, Ta = 25°C	_	7.5	11.0	
			Іссн	V _{CC} = 30 V, V _{DD} = 5.5 V, V _{IH} = 5 V	_	_	14.0	
Operating Power Supply Voltage		V _{CC}	V _{CCopr}		10	_	30	V

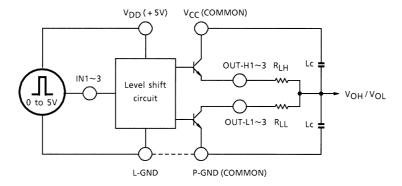
SWITCHING CHARACTERISTICS (Unless otherwise specified, $Ta = -20 \sim 70^{\circ}C$)

CHARACTERISTIC		PIN	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Propagation – Delay Time	High level	OUT-H1~3	tPLH	V_{DD} = 5.0 V, V_{CC} = 15 V R_{LH} = R_{LL} = 100 Ω , V_{IN} = 0.7 to 4 V	_	0.25	1.00	- µs
	Low level	OUT-L1~3	tPHL	$V_{DD} = 5.0 \text{ V}, V_{CC} = 15 \text{ V}$ $R_{LH} = R_{LL} = 100 \Omega$, $V_{IN} = 4 \text{ to } 0.7 \text{ V}$	_	0.25	1.00	

SWITCHING WAVEFORM



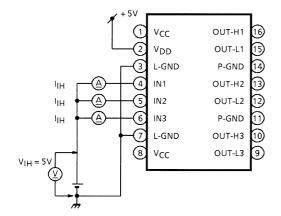
PROPAGATION DELAY TIME TEST CIRCUIT



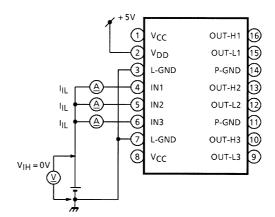
To shib a recommends connecting load resistors as in the above diagram, utilizing the independence of the high-level and low-level sides of this IC.

TEST CIRCUIT

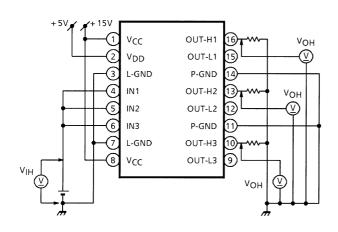
(1) I_{IH}



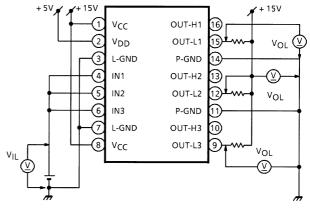
(2) I_{IL}



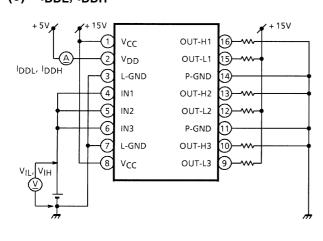
(3) V_{IH} , V_{OH}



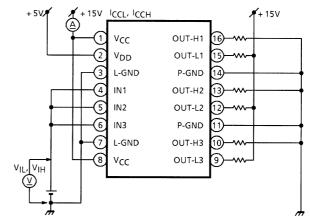
(4) V_{IL} , V_{OL}



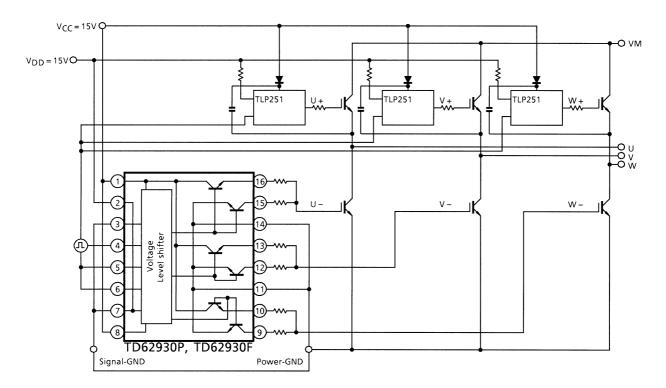
(5) I_{DDL}, I_{DDH}



(6) ICCL, ICCH



APPLICATION CIRCUIT



PRECAUTIONS for USING

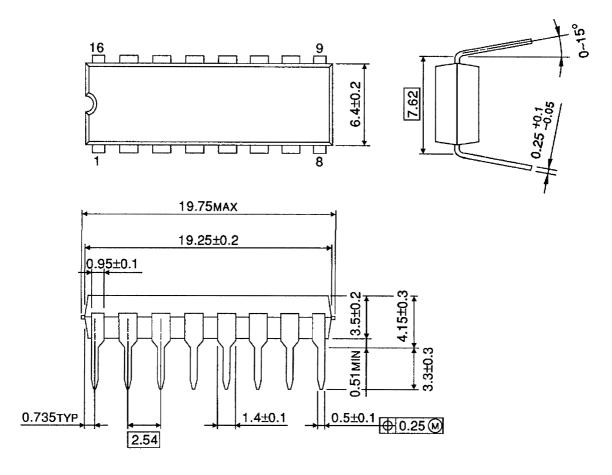
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

Utmost care is necessary in the design of the output line, VCC and GND (L-GND, P-GND) line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

PACKAGE DIMENSIONS

DIP16-P-300-2.54A Unit: mm



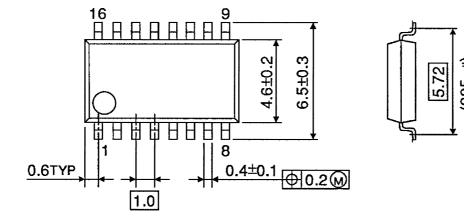
Weight: 1.11 g (Typ.)

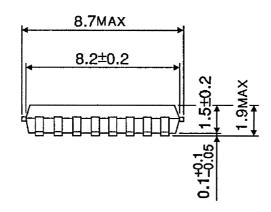
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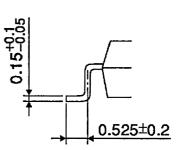
PACKAGE DIMENSIONS

SSOP16-P-225-1.00A

Unit: mm







Weight: 0.14 g (Typ.)

2001-07-05

RESTRICTIONS ON PRODUCT USE

000707EBA

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